



10 September 2026

Singapore Exchange Securities Trading Limited
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Singapore 068804

Telstra Group Limited
Office of the Company Secretary
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MELBOURNE VIC 3000
AUSTRALIA

ELECTRONIC LODGEMENT

Telstra announces CHF200 million bond issue

Telstra Group Limited (Telstra) priced a CHF200 million (approximately A\$342 million) bond issue (the Notes) on 9 September 2026 during London time. The Notes are issued under Telstra's Debt Issuance Program Offering Circular dated 18 August 2026. The Notes are expected to be issued on 30 September 2026 and have a 7-year maturity.

Telstra will use the proceeds from the Notes for general corporate purposes.

Authorised for release by:

Michael Ackland
Chief Financial Officer